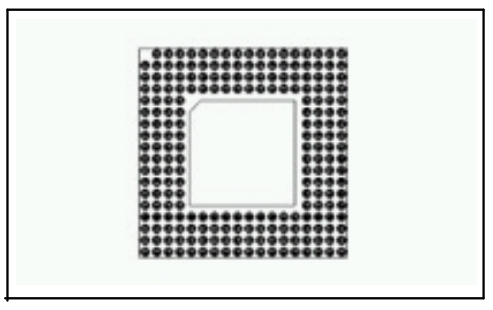
Product Details for 210815 -4



210815 -4

Active

PGA Sockets

Not Reviewed for ELV/RoHS Compliance

Product Highlights:

- Very Low Insertion Force
- Number of Positions = 223
- PCB Mount Style = Thru Hole
- Grid Size = 18x18
- Grid Spacing = Standard: 2.54 x 2.54 mm

View all Features

Quick Links

Check Pricing & Availability
Search for Tooling
Product Feature Selector
Contact Us About This Product

Documentation & Additional Information

Product Drawings:

- OPEN FRAME PGA 18x18, 223 SOCKETS (PDF, English)

Catalog Pages/Data Sheets:

- None Available

Product Specifications:

- None Available

Application Specifications:

- None Available

Instruction Sheets:

- None Available

CAD Files:

- None Available

List all Documents

Additional Information:

- Product Line Information

Related Products:

- Tooling

Product Features

(Please use the Product Drawing for all design activity)

Product Type Features:

- Insertion Force = Very Low
- Number of Positions = 223
- PCB Mount Style = Thru Hole
- Grid Size = 18x18
- Grid Spacing (mm [in]) = Standard: 2.54 x 2.54 [.100 x .100]
- Chip Compatibility = Other
- Frame Style = Open
- Sleeve Material = Brass
- Heat Sink Attachment = Without
- Profile = Standard
- Leg Style = Standard

Termination Related Features:

- Termination Post Length (mm [in]) = 2.84 [0.112]
- Socket Identifier = None

Body Related Features:

- Pick and Place Cover = None
- Socket Overall Height (mm [in]) = 4.46 [0.176]

Contact Related Features:

- Contact Style = Stamped + Formed
- Contact Material = Beryllium Copper
- Contact Mating Area Plating = Gold (30) 24c
- Contact Termination Area Plating = Tin Lead over Nickel
- Sleeve Plating = Tin -Lead (200) over nickel

Housing Related Features:

- Housing Color = Black
- Housing Material = Glass -Filled Thermoplastic Polyester
- Housing Flammability Rating = UL 94V -0
- Housing Material Temperature = High

Industry Standards:

- RoHS/ELV Compliance = Not reviewed for ELV/RoHS compliance
- Lead Free Solder Processes = Not reviewed for lead free solder process

Operation/Application:

- Application = Production

Packaging Related Features:

- Packaging Method = Tube

Other:

- Brand = AMP

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